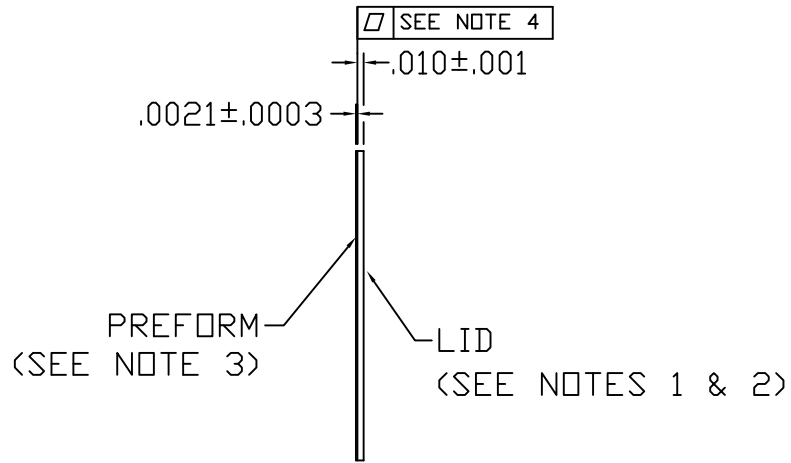
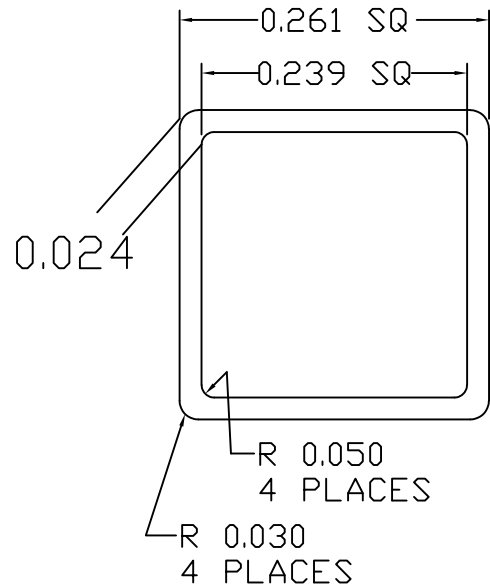


SSM P/N CL-26004



NOTES

1. MAT'L : KOVAR OR ALLOY 42
2. PLATING : 1st LAYER 50/350 MICROINCHES NI
2nd LAYER Au
3rd LAYER 50/350 MICROINCHES NI
4th LAYER 25 MICROINCHES MINIMUM Au

NOTES : TOTAL NICKEL LAYERS SHALL NOT EXCEED 450 MICROINCHES AND THE SUM OF BOTH GOLD LAYERS SHALL BE 50 MICROINCHES MINIMUM.

3. PREFORM - 80% ±1% Au
20% Sn
4. FLATNESS : ONE MIL (.001) MAXIMUM PER 1/2" T.I.R
5. TOLERANCES TO BE (XXX) 3 PLACES ±.003 UNLESS OTHERWISE NOTED

	DESCRIPTION	HI REL COMBO LID	
	PART NO	CL-26004	
Spectrum Semiconductor Materials, Inc. 155 Nicholson Lane San Jose, CA 95134 PH: (408) 435-5555 Fx: (408)435-8226	MATERION		
	MFG DRAWING NO TIC P435		

